

PMP10770 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C2, C3, C4, C5, C6	6	22uF	Std	Std	CAP, CERM, 22 μ F, 16 V, +/- 20%, X5R, 1206	1206
C7, C8	2	1000pF	Std	Std	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
C9, C10, C18	3	1uF	Std	Std	CAP, CERM, 1 μ F, 25 V, +/- 10%, X5R, 0402	0402
C11, C12, C13	3	0.1uF	Std	Std	CAP, CERM, 0.1 μ F, 16 V, +/- 10%, X7R, 0402	0402
C14, C15	2	560uF	EEF-GX0D561L	Panasonic	CAP, TA, 560 μ F, 2 V, +/- 20%, 0.003 ohm, SMD	SMD_7.3x1.9x4.3mm
C16	1	47uF	Std	Std	CAP, CERM, 47 μ F, 6.3 V, +/- 20%, X5R, 0805	0805
C17	1	10uF	Std	Std	CAP, CERM, 10 μ F, 6.3 V, +/- 20%, X5R, 0603	0603
C19, C20	2	4.7uF	Std	Std	CAP, CERM, 4.7 μ F, 16 V, +/- 10%, X5R, 0603	0603
C21	1	2200pF	Std	Std	CAP, CERM, 2200 pF, 25 V, +/- 10%, X7R, 0402	0402
J1	1		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
L1	1	450nH	XAL1010-451MEB	Coilcraft	Inductor, Shielded, Composite, 450 nH, 53 A, 0.0006 ohm, SMD	Inductor, 11.3x10x10mm
Q1, Q2	2		CSD87384M	Texas Instruments	Synchronous Buck NexFET Power Block II, MPB0005A	MPB0005A
R1, R2, R7, R8, R9, R10	6	0	Std	Std	RES, 0, 5%, 0.063 W, 0402	0402
R3, R5, R6	3	100k	Std	Std	RES, 100 k, 1%, 0.063 W, 0402	0402
R4	1	6.98k	Std	Std	RES, 6.98 k, 1%, 0.063 W, 0402	0402
R11	1	30.1k	Std	Std	RES, 30.1 k, 1%, 0.063 W, 0402	0402
R12	1	11.3k	Std	Std	RES, 11.3 k, 1%, 0.063 W, 0402	0402
R13	1	69.8k	Std	Std	RES, 69.8 k, 1%, 0.063 W, 0402	0402
R14	1	187k	Std	Std	RES, 187 k, 1%, 0.063 W, 0402	0402
R15	1	3.01	Std	Std	RES, 3.01 ohm, 1%, 0.125W, 0805	0805
T1, T2	2	50A	CB35-36-CY	Panduit	Terminal 50A Lug	CB35-36-CY
TP1, TP3, TP4	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP2, TP5	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		TPS53219A	Texas Instruments	Wide Input Voltage, Eco-mode, Single Synchronous Step-Down Controller, RGT0016A	RGT0016A

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